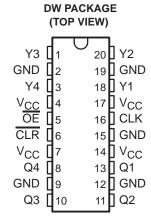
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- Low Output Skew, Low Pulse Skew for Clock-Distribution and Clock-Generation Applications
- TTL-Compatible Inputs and CMOS-Compatible Outputs
- Distributes One Clock Input to Eight Outputs
 - Four Same-Frequency Outputs
 - Four Half-Frequency Outputs
- Distributed V_{CC} and Ground Pins Reduce Switching Noise
- High-Drive Outputs (-48-mA I_{OH}, 48-mA I_{OL})
- State-of-the-Art EPIC-IIB™ BiCMOS Design Significantly Reduces Power Dissipation
- Package Options Include Plastic Small-Outline (DW)



description

The CDC337 is a high-performance, low-skew clock driver. It is specifically designed for applications requiring synchronized output signals at both the clock frequency and one-half the clock frequency. The four Y outputs switch in phase and at the same frequency as the clock (CLK) input. The four Q outputs switch at one-half the frequency of CLK.

When the output-enable (\overline{OE}) input is low and the clear (\overline{CLR}) input is high, the Y outputs follow CLK and the Q outputs toggle on low-to-high transitions at CLK. Taking \overline{CLR} low asynchronously resets the Q outputs to the low level. When \overline{OE} is high, the outputs are in the high-impedance state.

The CDC337 is characterized for operation from -40°C to 85°C.

FUNCTION TABLE

	INPUTS	OUT	PUTS	
OE	CLR	CLK	Y1-Y4	Q1-Q4
Н	Х	Χ	Z	Z
L	L	L	L	L
L	L	Н	Н	L
L	Н	L	L	Q ₀ †
L	Н	\uparrow	Н	\overline{Q}_0 †

[†] The level of the Q outputs before the indicated steady-state input conditions were established

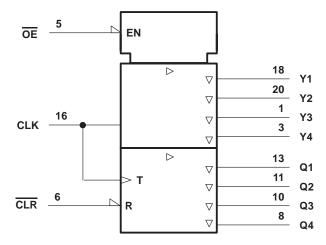


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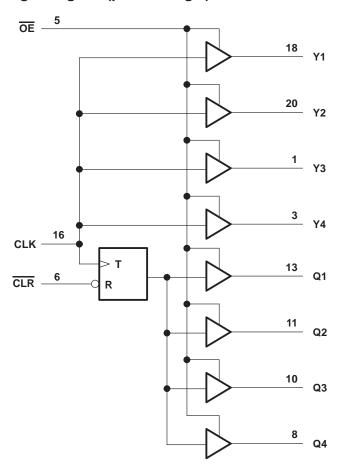


logic symbol[†]



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[‡]

Supply voltage range, V _{CC}	
Voltage range applied to any output in the high state or power-off state,	
V _O (see Note 1)	$-0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Current into any output in the low state, I _O	96 mA
Input clamp current, I _{IK} (V _I < 0)	–18 mA
Maximum power dissipation at $T_A = 55^{\circ}C$ (in still air) (see Note 2)	1.6 W
Storage temperature range, T _{stq}	–65°C to 150°C

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, refer to the Package Thermal Considerations application note in the 1994 ABT Advanced BiCMOS Technology Data Book, literature number SCBD002B.



recommended operating conditions (see Note 3)

		MIN	MAX	UNIT
VCC	Supply voltage	4.75	5.25	V
VIH	High-level input voltage	2		V
V _{IL}	Low-level input voltage		0.8	V
VI	Input voltage	0	VCC	V
loн	High-level output current		-48	mA
loL	Low-level output current		48	mA
fclock	Input clock frequency		80	MHz
TA	Operating free-air temperature	-40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDIT	MIN	TYP [†]	MAX	UNIT		
VIK	$V_{CC} = 4.75 \text{ V},$	I _I = -18 mA					-1.2	V
Voн	$V_{CC} = 4.75 \text{ V},$	$I_{OH} = -32 \text{ mA}$			3.75			V
V _{OL}	$V_{CC} = 4.75 \text{ V},$	$I_{OL} = 32 \text{ mA}$					0.55	V
lН	$V_{CC} = 5.25 \text{ V},$	V _I = 2.7 V			50	μΑ		
I _{IL}	$V_{CC} = 5.25 \text{ V},$	V _I = 0.5 V				-50	μΑ	
loz	$V_{CC} = 5.25 \text{ V},$	$V_O = V_{CC}$ or GND					±50	μΑ
				Outputs high			70	
Icc	$V_{CC} = 5.25 \text{ V},$	$V_I = V_{CC}$ or GND, Ic	O = 0	Outputs low			85	mA
				Outputs disabled			70	
Ci	V _I = 2.5 V or 0.5 V		3		pF			
Co	$V_O = VCC \text{ or GNI}$		10		pF			

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

			MIN	MAX	UNIT
fclock	Clock frequency			80	MHz
		4			
t _W	Pulse duration CLK low				ns
		4			
t _{su}	Setup time, CLR inactive before CLK↑		2		ns
	Clock duty cycle		40%	60%	



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switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Note 4 and Figures 1 and 2)

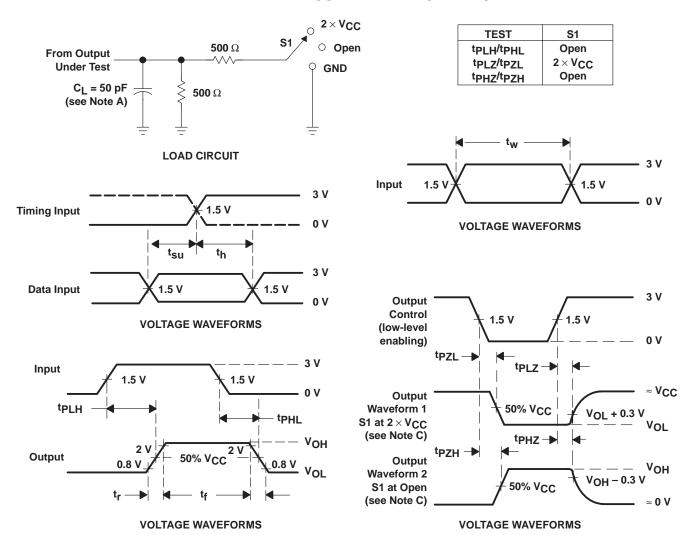
PARAMETER	FROM (INPUT)	TO (OUTPUT)	MIN	түр†	MAX	UNIT
fmax			80			MHz
t _{PLH}	CLK	Any Y or Q	4		9	no
t _{PHL}		Any Y or Q	4		9	ns
^t PHL	CLR	Any Q	4		10	ns
^t PZH	- OE	Any Vor O	3		7	
^t PZL	OE	Any Y or Q	3		7	ns
^t PHZ	ŌĒ	Any Y or Q	2		7	no
t _{PLZ}	- OE	Any For Q	2		7	ns
		Y↑			0.75	
t _{sk(o)}	CLK↑	Q↑			0.9	ns
, ,		Y↑ and Q↑			0.9	
t _r				0.9		ns
t _f				0.7		ns

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

NOTE 4: All specifications are valid only for all outputs switching.



PARAMETER MEASUREMENT INFORMATION



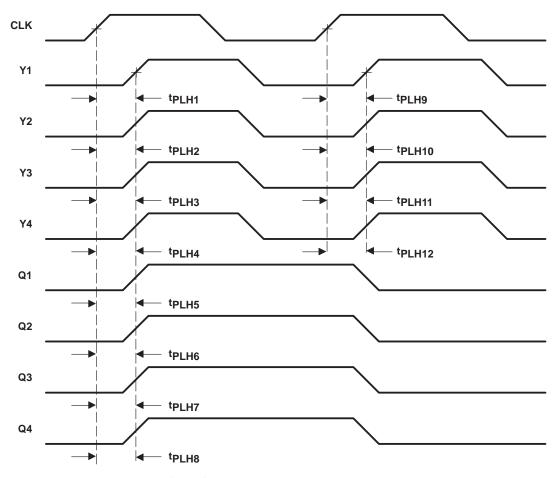
NOTES: A. C_L includes probe and jig capacitance.

- B. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_{O} = 50 \Omega$, $t_{f} \leq 2.5 \text{ ns}$, $t_{f} \leq 2.5 \text{ ns}$.
- C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



PARAMETER MEASUREMENT INFORMATION



- NOTES: A. Output skew, $t_{Sk(0)}$, from CLK \uparrow to Y \uparrow , is calculated as the greater of the difference between the fastest and slowest of t_{PLHn} (n = 1, 2, 3, 4) or t_{PLHn} (n = 9, 10, 11, 12).

 B. Output skew, $t_{Sk(0)}$, from CLK \uparrow to Q \uparrow , is calculated as the greater of the difference between the fastest and slowest of
 - t_{PLHn} (n = 5, 6, 7, 8).
 - C. Output skew, $t_{sk(0)}$, from CLK \uparrow to Y \uparrow and Q \uparrow , is calculated as the greater of the difference between the fastest and slowest of t_{PLHn} (n = 1, 2, ..., 8).

Figure 2. Waveforms for Calculation of tsk(o)

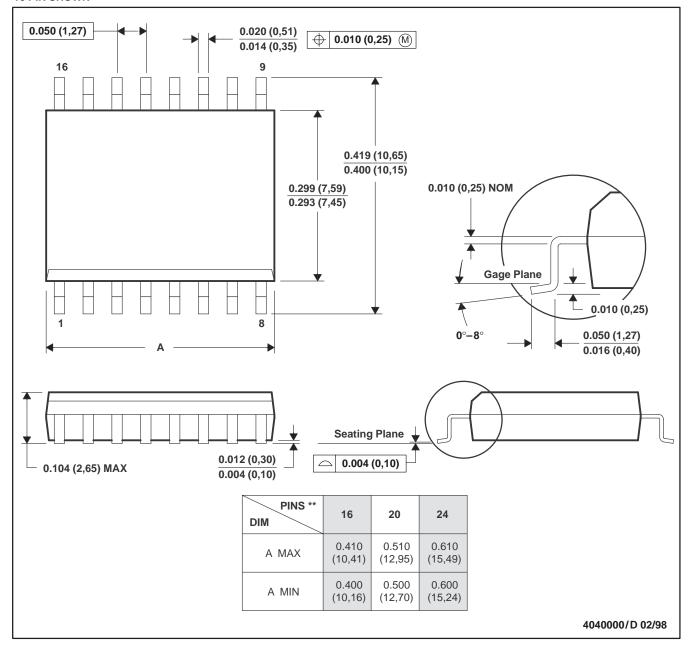


MECHANICAL INFORMATION

DW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

16 PIN SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013







www.ti.com 7-Jun-2010

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
CDC337DBLE	OBSOLETE	SSOP	DB	20		TBD	Call TI	Call TI	Samples Not Available
CDC337DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Request Free Samples
CDC337DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Request Free Samples
CDC337DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
CDC337DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
CDC337NS	OBSOLETE	so	NS	20		TBD	Call TI	Call TI	Samples Not Available
CDC337NSG4	OBSOLETE	so	NS	20		TBD	Call TI	Call TI	Samples Not Available

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

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the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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PACKAGE OPTION ADDENDUM

7-Jun-2010

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TAPE AND REEL INFORMATION





Α	0	Dimension designed to accommodate the component width
В	0	Dimension designed to accommodate the component length
		Dimension designed to accommodate the component thickness
٧	٧	Overall width of the carrier tape
ГР	1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device		Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CDC337DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1





*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CDC337DWR	SOIC	DW	20	2000	346.0	346.0	41.0

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